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SemiWiki Podcast – An expert panel discussion on the move to chiplets

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By John McMillan

Listen in as Tony Mastroianni Advanced Packaging Solutions Director – Siemens EDA along with Saif Alam Vice President of Engineering at Movellus Inc. and Craig Bishop – CTO Deca Technologies join SemiWiki's founder Daniel Nenni to discuss chiplets and 2.5/3D design in episode EP179 of the Semiconductor Insiders podcast.

In this informative podcast, the panel digs into the move to chiplets. Why it's happening now and who can benefit from the trend are discussed in detail, along with considerations for ecosystem management. design methodology, the role of standards, and addressing the risks associated with this new design style.

In this podcast the panel discusses:

- Why chiplets are needed, and who needs them.
- How people design 2.5D today.
- The risks involved with 2.5D and 3D IC design.
- Provides insights into the future of chiplets.

This podcast episode is available to stream or download on SemiWiki's site Click Here as well as other popular podcast platforms.

To learn more about Siemens 3D IC visit our 3D IC design solutions website.

Also visit the Siemens 3D IC podcast to listen in as industry experts discuss 3D IC concepts and the latest trends: chiplet designs, IC packaging, multi-die verification, golden netlists, electrical signoff, system analysis, and more!

3D IC Podcast

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